

CH03-CJ - SIM CARD HOLDER, CONTACT TYPE, WITHOUT SWITCH, 8 PINS

FEATURES

- 1. GENERAL CHARACTERISTICS
 DIMENSIONS: 23.62L x 10.16W x 1.3H mm
 WEIGHT: APPROX. 0.5±0.1g
 CONTACT PRINCIPLE: FRICTION TECHNOLOGY
 MOUNTING SYSTEM: SMT TYPE OPTIONAL POST
 DURABILITY: 100,000 CYCLES MIN.

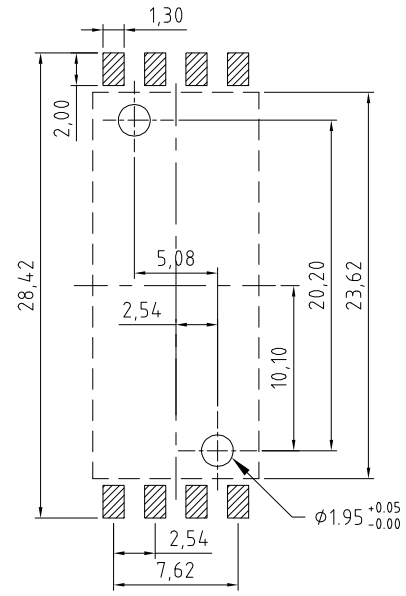
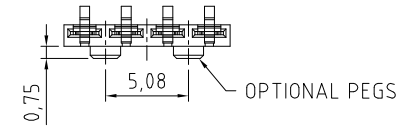
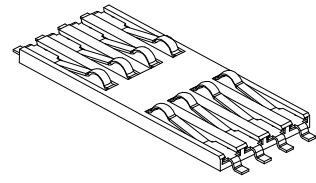
- 2. MECHANICAL CHARACTERISTICS
 INSULATION MATERIAL: THERMOPLASTIC, UL 94V-0
 CONTACT MATERIAL: PHOSPHOR BRONZE
 CONTACT AREA PLATING: GOLD FLASH OVER NICKEL

- 3. ELECTRICAL CHARACTERISTICS
 CONTACT RESISTANCE: 50m OHMS TYP. 100m OHMS MAX.
 INSULATION RESISTANCE: >1000M OHMS / 500V DC
 RATED CURRENT: 1A MAX, 10uA MIN.
 RATED VOLTAGE: 50V MAX.
 WITHSTANDING DIELECTRIC VOLTAGE: 500V AC R.M.S. FOR 1 MINUTE

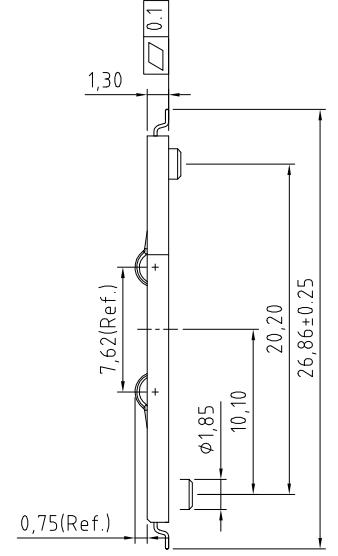
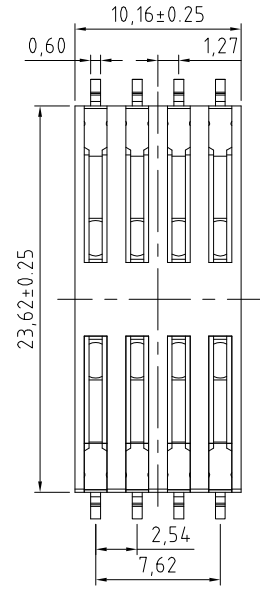
- 4. SOLDERABILITY
 WAVE: NOT APPLICABLE
 IR REFLOW: 250°C, 5 SEC. MAX.
 MANUAL SOLDERING: 360°C, 3 SEC. MAX.

- 5. ENVIRONMENTAL CHARACTERISTICS
 OPERATING TEMPERATURE: -40°C ~ +85°C
 OPERATING HUMIDITY: 10% ~ 95% RH
 STORAGE TEMPERATURE: -40°C ~ +85°C
 STORAGE HUMIDITY: 10% ~ 95% RH
 THERMAL SHOCK: -40°C ~ +85°C, 5 CYCLES
 DAMP HEAT: 40°C, 90% RH, 240HR
 SALT-MIST: 35°C, 5% NaCl, 24HR

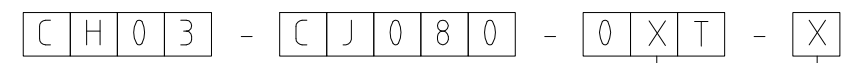
- NOTES:
- 1. ACCEPTABLE SIM CARD SIZE SHOULD MEET GSM 11.11 SPECIFICATION REQUIREMENT.
 - 2. PACKAGING: 1,000PCS/REEL.



COMPONENT SIDE (TOLERANCE: ±0.05)
RECOMMENDED PCB LAYOUT



HOW TO ORDER



- LOCATING PEG OPTIONS:
 A = WITH PEGS
 B = WITHOUT PEG
- 'H' HEIGHT OPTIONS:
 A = 1.30MM

REV. DATE & DRN	10 26/10/11 - NYW RELEASE
	11 28/11/14 - NYW
	12 09/08/17 - NYW
	13 19/02/19 - NYW
	14 10/02/19 - NYW

Scale: 3:1	THIRD ANGLE	Unstated Tolerances: X ±0.35 .X ±0.25 .XX ±0.15 XXX ±0.10	Material SEE NOTE
Drawn: NYW		Title SIM CARD ACCEPTOR	NOT TO SCALE
App'd: XXXX	Revision: 1.3	Unit: mm	
Date: 18 FEB. '19			

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Type: CH03-CJ
CH03-CJ
Drawing Number:
Sheet 1 of 1
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